

1-29. (Cancelled).

30. (Currently Amended) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;
an opening in said substrate, said opening consisting of defined by said substrate material,
wherein said borders of said substrate material form a first rectangular portion and a second
rectangular portion, wherein said second rectangular portion has larger dimensions in a
horizontal direction than said first rectangular portion, wherein said horizontal direction is
between sidewalls of said first rectangular portion and said second rectangular portion, wherein
said sidewalls are perpendicular to said upper surface; and
a conductor filling said opening.

31. (Previously Presented) The integrated circuit in claim 30, wherein said second rectangular portion is deeper in said opening than said first rectangular portion.

32. (Previously Presented) The integrated circuit in claim 30, wherein said first rectangular portion is deeper in said opening than said second rectangular portion.

33. (Currently Amended) The integrated circuit in claim 30, wherein said lateral openings
second rectangular portion increases increase a surface area of said trench capacitor opening.

34. (Currently Amended) The integrated circuit in claim 30, wherein said ~~lateral openings~~ ~~second rectangular portion increases~~ ~~increase~~ a capacitance of said structure.

35. (Currently Amended) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;
an opening in said substrate, ~~said opening consisting of~~ defined by borders of said
substrate material, wherein said borders of said substrate material form a first rectangular portion,
a second rectangular portion, and a third rectangular portion, wherein said second rectangular
portion has larger dimensions in a horizontal direction than said first rectangular portion and said
third rectangular portion, wherein said horizontal direction is between sidewalls of said first
rectangular portion and said second rectangular portion, wherein said sidewalls are perpendicular
to said upper surface; and
a conductor filling said opening.

36. (Previously Presented) The integrated circuit in claim 35, wherein said second rectangular
portion is between said first rectangular portion and said third rectangular portion.

37. (Previously Presented) The integrated circuit in claim 35, wherein said first rectangular
portion and said third rectangular portion have substantially similar dimensions.

38. (Currently Amended) The integrated circuit in claim 35, wherein said ~~lateral openings~~ ~~second rectangular portion increases~~ ~~increase~~ a surface area of said structure.

39. (Currently Amended) The integrated circuit in claim 35, wherein said first rectangular portion and said third rectangular portion have different dimensions in said horizontal direction.

40. (Currently Amended) An integrated circuit structure comprising:
a substrate having an upper surface, wherein said substrate comprises a substrate material;
a bottle-shaped opening in said substrate, ~~said bottle-shaped opening comprising defined borders of said substrate material, wherein said borders of said substrate material form~~ a first rectangular portion and a second rectangular portion, wherein said second rectangular portion has larger dimensions in a horizontal direction than said first rectangular portion, wherein said horizontal direction is between sidewalls of said first rectangular portion and said second rectangular portion, wherein said sidewalls are perpendicular to said upper surface; and
a conductor filling said opening.

41. (Previously Presented) The integrated circuit in claim 40, wherein said second rectangular portion is deeper in said opening than said first rectangular portion.

42. (Previously Presented) The integrated circuit in claim 40, wherein said first rectangular portion is deeper in said opening than said second rectangular portion.

43. (Currently Amended) The integrated circuit in claim 40, wherein said lateral openings second rectangular portion increases increase a surface area of said trench capacitor bottle-shaped

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opening.

44. (Currently Amended) The integrated circuit in claim 40, wherein said ~~lateral openings~~
second rectangular portion increases a capacitance of said structure.